



FIGURE 1



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A cross-sectional view of a device assembly. It features a central rectangular component labeled 'IC' (Integrated Circuit) with diagonal hatching. This IC is mounted on a substrate labeled '20' with a cross-hatch pattern. A layer labeled 'G' is positioned between the IC and the substrate. A line points from the label '20' to the substrate, and another line points from the label 'G' to the layer between the IC and the substrate.

Fig. 2

090704Z JUL 68